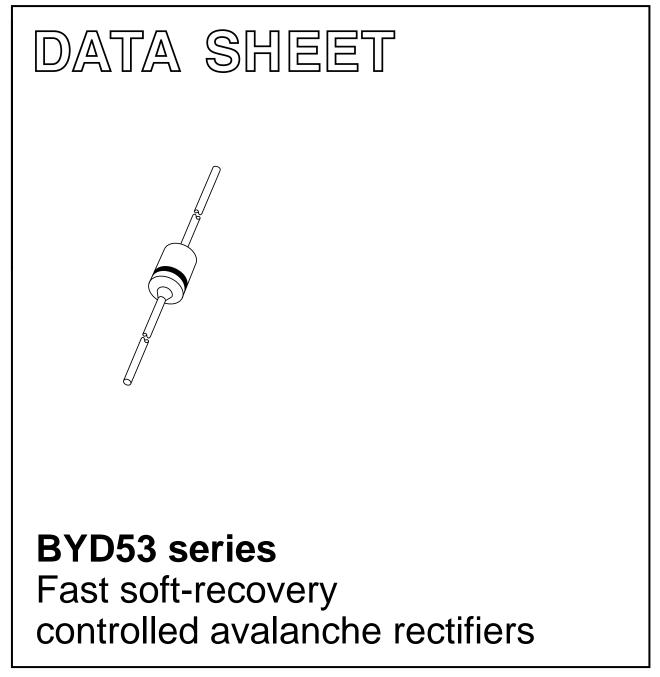
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 1996 Jun 05 File under Discrete Semiconductors, SC01 1996 Sep 18



Philips Semiconductors

Fast soft-recovery controlled avalanche rectifiers

FEATURES

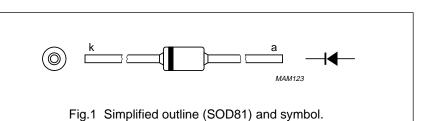
- Glass passivated
- High maximum operating temperature
- Low leakage current
- Excellent stability
- Guaranteed avalanche energy absorption capability
- Available in ammo-pack.

DESCRIPTION

Cavity free cylindrical glass SOD81 package through Implotec^{TM(1)} technology. This package is

hermetically sealed and fatigue free as coefficients of expansion of all used parts are matched.

(1) Implotec is a trademark of Philips.



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{RRM}	repetitive peak reverse voltage				
	BYD53U		_	1200	V
	BYD53V		_	1400	V
V _R	continuous reverse voltage				
	BYD53U		_	1200	V
	BYD53V		_	1400	V
I _{F(AV)}	average forward current	T _{tp} = 55 °C; lead length = 10 mm see Fig.2; averaged over any 20 ms period; see also Fig.6	_	0.85	A
		T _{amb} = 65 °C; PCB mounting (see Fig.11); see Fig.3; averaged over any 20 ms period; see also Fig.6	_	0.45	A
I _{FRM}	repetitive peak forward current	T _{tp} = 55 °C; see Fig.4	_	8.25	A
		T _{amb} = 65 °C; see Fig.5	_	4.45	A
I _{FSM}	non-repetitive peak forward current	t = 10 ms half sine wave; $T_j = T_{j max}$ prior to surge; $V_R = V_{RRMmax}$	-	5	A
E _{RSM}	non-repetitive peak reverse avalanche energy	L = 120 mH; $T_j = T_{j max}$ prior to surge; inductive load switched off	_	10	mJ
T _{stg}	storage temperature		-65	+175	°C
Tj	junction temperature	see Fig.7	-65	+175	°C

ELECTRICAL CHARACTERISTICS

 $T_j = 25 \ ^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _F	forward voltage	$I_F = 1 \text{ A}; T_j = T_{j \text{ max}}; \text{ see Fig.8}$	_	_	1.7	V
		I _F = 1 A; see Fig.8	_	—	2.3	V
V _{(BR)R}	reverse avalanche breakdown voltage	I _R = 0.1 mA				
	BYD53U		1300	-	-	V
	BYD53V		1500	-	-	V
I _R	reverse current	$V_R = V_{RRMmax}$; see Fig.9	-	—	1	μA
		V _R = V _{RRMmax} ; T _j = 165 °C; see Fig.9	_	_	100	μA
t _{rr}	reverse recovery time	when switched from $I_F = 0.5 A$ to $I_R = 1 A$; measured at $I_R = 0.25 A$; see Fig.12	_	_	150	ns
C _d	diode capacitance	f = 1 MHz; V _R = 0 V; see Fig.10	_	20	_	pF
dI _R dt	maximum slope of reverse recovery current	when switched from $I_F = 1$ A to $V_R \ge 30$ V and $dI_F/dt = -1$ A/µs; see Fig.13	_	_	5	A/μs

THERMAL CHARACTERISTICS

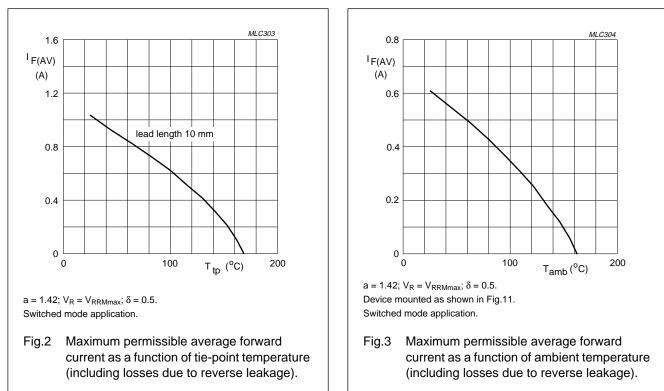
SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-tp}	thermal resistance from junction to tie-point	lead length = 10 mm	60	K/W
R _{th j-a}	thermal resistance from junction to ambient	note 1	120	K/W

Note

1. Device mounted on an epoxy-glass printed-circuit board, 1.5 mm thick; thickness of Cu-layer ≥40 μm, see Fig.11. For more information please refer to the *'General Part of Handbook SC01'*.

BYD53 series

GRAPHICAL DATA



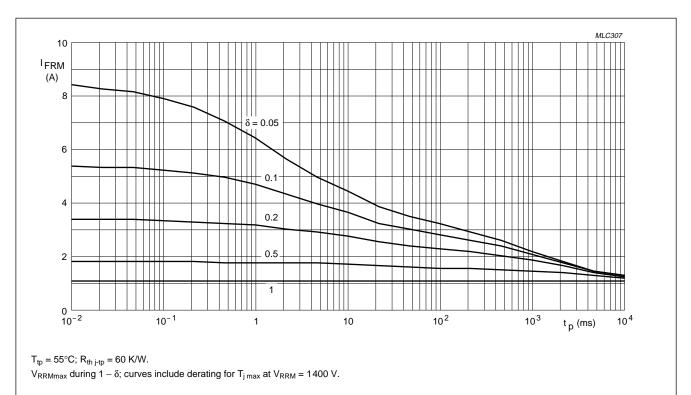
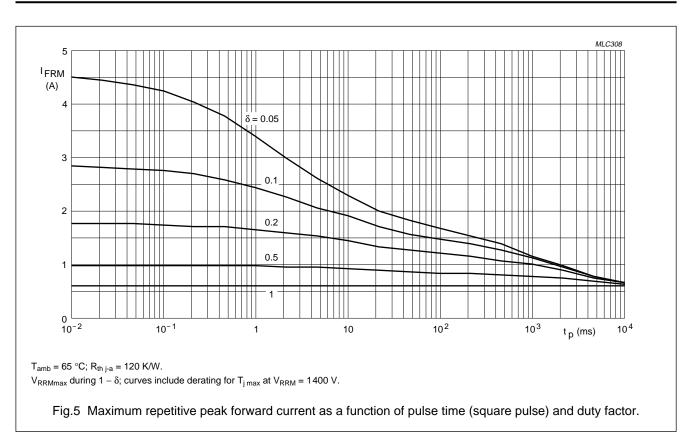
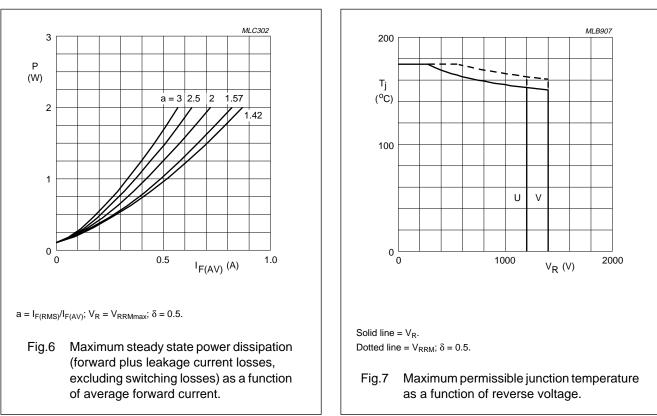
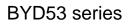
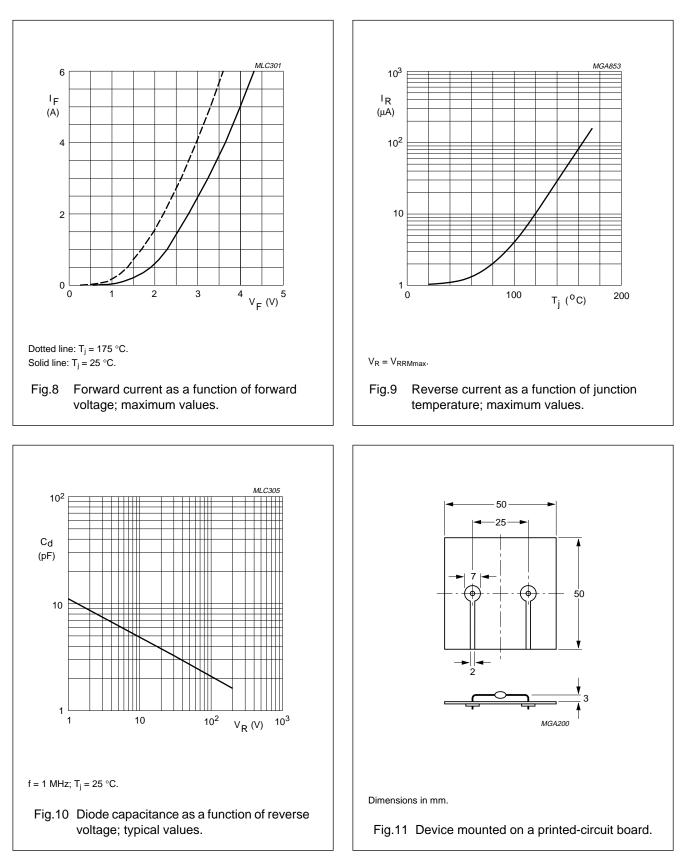


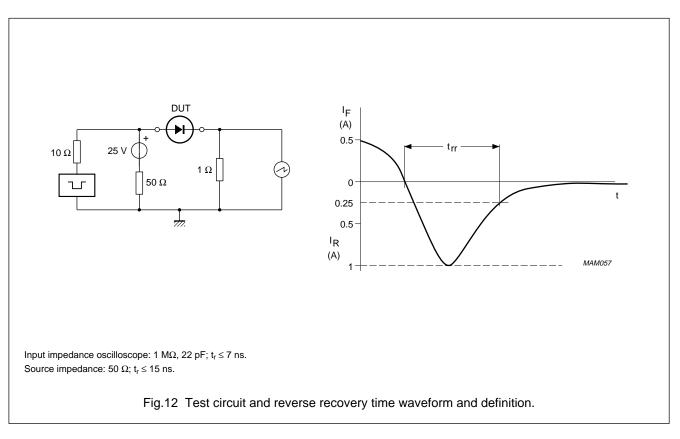
Fig.4 Maximum repetitive peak forward current as a function of pulse time (square pulse) and duty factor.

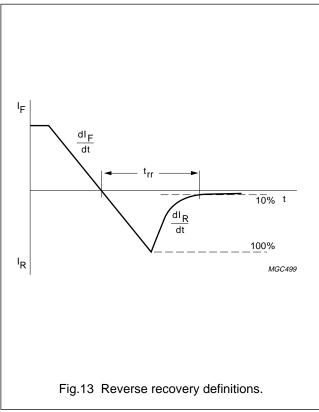






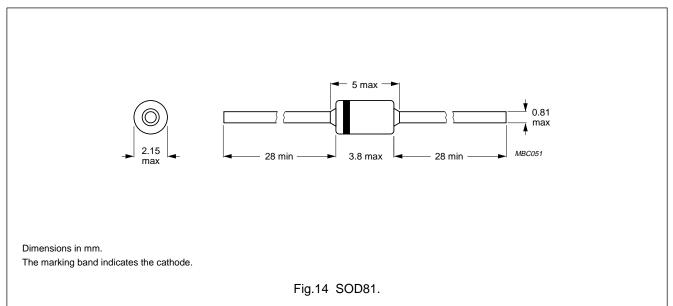






BYD53 series

PACKAGE OUTLINE



DEFINITIONS

Data Sheet Status			
Objective specification	This data sheet contains target or goal specifications for product development.		
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.		
Product specification	This data sheet contains final product specifications.		
Limiting values			
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.			
Application information			
Where application information is given, it is advisory and does not form part of the specification.			

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.